

Product Bulletin

Document # : PB22162Z Issue Date: 14 February 2018

Title of Change:	NCV7535 Datasheet Update	
Effective date:	14 February 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <nixon.mathew@onsemi.com></nixon.mathew@onsemi.com>	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change category:	☐ Wafer Fab Change ☐ Assembly Change	☐ Test Change ☐ Other: <u>Datasheet update</u>
Change Sub-Category(s): Manufacturing Site Change/Acturing Process Change		□ Datasheet/Product Doc change □ Shipping/Packaging/Marking □ Other:
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None
Description and Purpose:		
Features list updated • "AEC-Q100 Qualified and PPAP Capable" sentence added		
 Absolute Maximum Ratings updated Vmax_diglO Max limits updated for EN and CSN pins from "VCC+0.3 V" to "5.8 V" -> Maximum value not changed, only different interpretation linj_diglO parameter added 		
 SPI Registers descriptions updated GLOBAL STATUS BYTE CONTENT – NRDY bit description extended ("This bit indicates that the driver cannot be activated and the chargepump is switched off.") STATUS_0.VSUV description updated (note that this bit is latched was added) STATUS_0.VSOV description updated (note that this bit is latched was added) 		
 Editorial corrections Typos in Figure 7 fixed (incorrect numbers of the data bits) Typos in CONFIG register (page 17) fixed (incorrect bit names) 		
The change will not impact form, fit, or function of product.		
List of Affected Standard Parts:		
NCV7535DBR2G		

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